

REMARKS

As an initial matter, Applicants gratefully acknowledge the Examiner's determination that claims 38 and 49-54 are allowed (Office Action, dated October 4, 2002, page 10, lines 4-14).

Claims 29, 31, 36, 37 and 55-62 have been canceled without prejudice so that the only remaining claims are the allowed claims 38 and 49-54.

The specification has been amended so that character reference "4" in Figure 1b is in the specification. Applicants have removed character reference "3" from Figure 1a, and this amendment to the drawings is described in a separate attached paper as required by 37 C.F.R. 1.1.121. Therefore, Applicants believe they have overcome the Examiner's objections to the specification and drawings set forth in the previous Office Action, dated October 4, 2002, on page 2.

Applicants believe that the present amendment adds no new matter to the application.

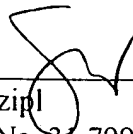
In view of the present amendment, Applicants respectfully request reconsideration and allowance of claims 38 and 49-54 for the reasons of record.

Because the present application contains only allowed claims 38 and 49-54, the application is in condition for allowance and a prompt Notice of Allowance is earnestly solicited. Questions are welcomed by the below signed attorney for the Applicants.

Serial No. 09/785,436

Respectfully submitted,

GRIFFIN & SZIPL, P.C.

A handwritten signature in black ink, appearing to be 'JS', written over a horizontal line.

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MARKED UP VERSION SHOWING CHANGES

IN THE SPECIFICATION

Please amend the specification as follows.

1. Please replace the paragraph on page 3, line 21 to page 4, line 1, with the following new paragraph:

The filmy organic die-bonding material 1 is contact-bonded to a die pad 6 of a lead frame 5 on a heating platen 7 by means of a contact press ~~4 as shown~~^(b) in Fig. 1(b). The contact bonding may preferably be carried out under conditions of a temperature of from 100°C to 250°C, a press time of from 0.1 second to 20 seconds and a pressure of from 4 gf/mm² to 200 gf/mm².

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